



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: **1752**

Serial No.: **10/629,806**

Examiner: **Sin J. Lee**

Filed: **July 30, 2003**

Confirmation Number: **9494**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR
FORMING RESIST PATTERN, AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: **030923**

Customer Number: **38834**

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

September 29, 2005

Sir:

In response to the Office Action dated April 29, 2005, the response due date extended to September 29, 2005 by a 2-months Extension of Time, please amend the above-identified application as follows:

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 9 of this paper.